



Sierra Components, Inc.

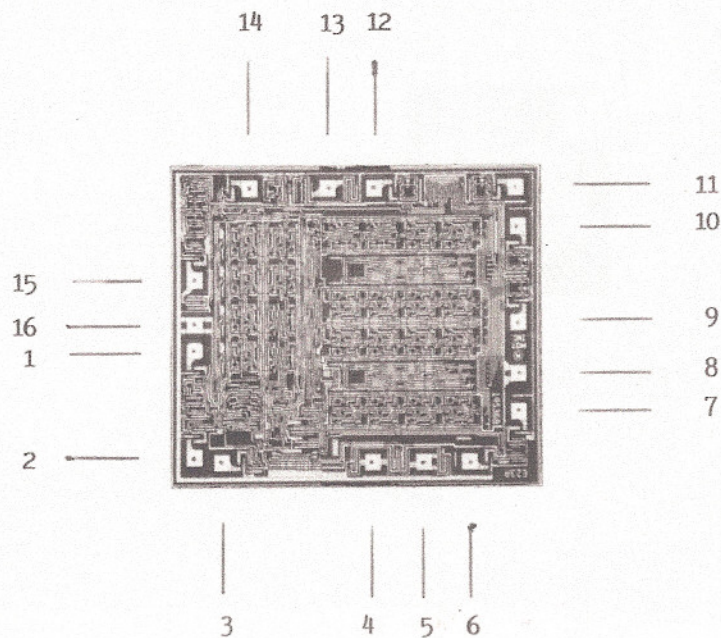
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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

DEVICE	CATEGORY	MANUFACTURER	REV. NO.
MCC14536B	CMOS-LOGIC	MOTOROLA	MASK NO.

STANDARD PACKAGE: 16 PIN DIL

Metal Print: 14536B
 E23A
 MOT. INC



PIN/PAD FUNCTION:

- | | |
|--------------|-------------|
| 1. SET | 9. A |
| 2. RESET | 10. B |
| 3. IN 1 | 11. C |
| 4. OUT 1 | 12. D |
| 5. OUT 2 | 13. DECODE |
| 6. 8- BYPASS | 14. OSC INH |
| 7. CLOCK INH | 15. MONO IN |
| 8. VSS | 16. VDD |

Top Material: Al
 Backside Material: Si
 Bond Pad Size:
 Backside Potential:
 Mask Ref:

APPROVED BY: **MG**

DIE SIZE : **101 X 87 mils.**

DATE: **3/23/07**

MFG:

THICKNESS:

MCC14536B

P/N: **Motorola**